

Korea Lunar Exploration Program**DTN****SBC Worst Case Analysis**

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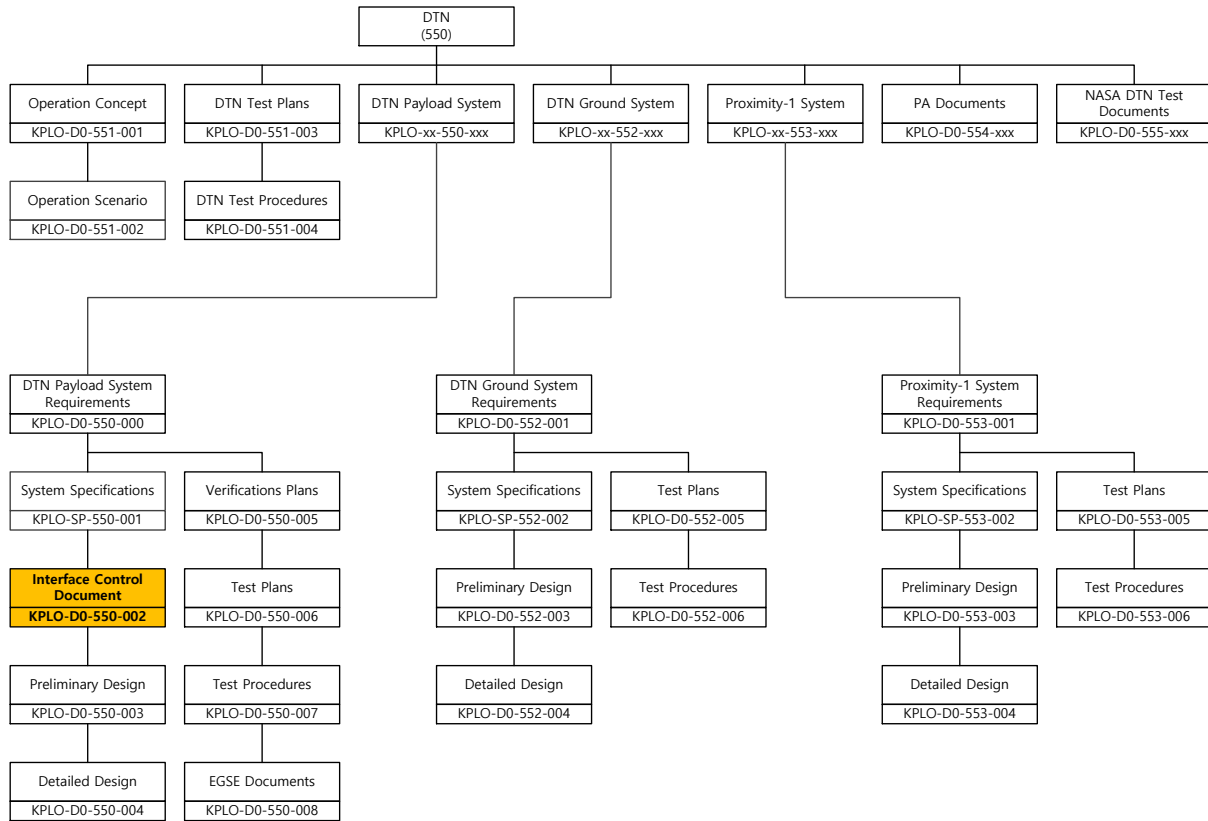
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1 INTRODUCTION

1.1 SCOPE

This document summarizes Part Stress Analysis for the Single Board Computer (SBC) to be developed for the DTN. Part Stress analysis procedures and documentation shall be performed in accordance with PAR

1.2 DTN Overview

The mission of DTN is to validate DTN communication protocols by space-link testing through KPLO. So DTN operations are focused on testing the DTN protocols using KPLO space-links.

2 DOCUMENTS

2.1 APPLICABLE DOCUMENTS

	Document No.	Title
AD-1	KPLO-D0-210-003	User Requirements Document (KARI)
AD-2	KPLO-D0-524-008	User Requirements Document (ETRI)

2.2 REFERENCE DOCUMENTS

	Document No.	Title
RD-1	MIL-STD-461E	Requirements for the Control of Electromagnetic Interference Characteristics of Subsystems and Equipment
RD-2	MIL-STD-462D	Measurements of Electromagnetic Interference Characteristics
RD-3	ECSS-E-ST-10-06C	Space engineering Technical Requirements specification
RD-4	ECSS-Q-60-11A	Derating and End of Life parameter drifts-EEE Components
RD-5	MIL-HDBK-217	Reliability Prediction for Electronic Equipment
RD-6	ESA PSS-01-301	Derating Requirement and Application Rules for Electronic Components

3 ACRONYMS AND ABBREVIATIONS

AMS	Asynchronous Message Service
AOS	Advanced Orbiting System
BP	Bundle Protocol
BSS	Bundle Streaming Service
CCSDS	Consultative Committee for Space Data Systems
CFDP	CCSDS File Delivery Protocol
DCC	DTN Control Center
DTN	Delay(Disruption) Tolerant Network
DTNPL	DTN Payload
IP	Internet Protocol
KPLO	Korea Pathfinder Lunar Orbiter
LCM	Lander Communication Model
LTP	Liklider Transmission Protocol
M&C	Monitor & Control
RCM	Rover Communication Model
SLE	Space Link Extension
TBC	To Be Confirmed
TBD	To Be Defined
TCP	Transmission Control Protocol
UDP	User Datagram Protocol

4 Method

4.1 Approach

The Worst Case Analysis (WCA) evaluates the range of functional performance that will be experienced as a result of variations in component and operational tolerances. The analysis assumes that all components are in good working order and that they have assembled correctly.

The WCA is structured in 3 levels :

- (i) The evaluation of the components total parametric variation (DP)
(resulting from initial tolerance, temperature, aging and radiation drifts)
- (ii) The analysis of circuit functional blocks, based on the DP of the used components
- (iii) The analysis of the interface inputs and loads Derating requirements are provided in the clause 6 for each component family.

4.2 Parametric variations and tolerances

The total parametric variation of an electronic component depends on variations resulting from a number of causes. Therefore the WCA requires knowledge of the total part variations over the life and environmental extremes of the particular project.

The following effect will be taken into account

- (i) Component Initial Tolerance
The tolerance to which the manufacturer has screened the component nominal value.

- (ii) Component aging drift (End-of-Life Tolerance)
The aging of electronic parts is a continuing process of chemical change. This parameter is either mentioned as a drift in ppm/year or as an End-Of-Life (EOL) absolute tolerance. The absolute parametric drift is calculated for a lifetime of 10 years.

- (iii) Temperature drift
The upper temperature extreme to which parts are to be analyzed shall be based on a thermal analysis for an 85°C design. The lower analysis temperature extreme shall be at -20°C. The WCA is calculated for a nominal temperature of 25°C and a range from -35°C to +85°C.
Temp = -20°C < 25°C < 85°C
The temperature difference are therefore +60°C and -+45°C.

- (iv) Radiation drift
Passive components are not subject to degradation at typical space exposures of total dose radiation levels. Semiconductors, however, are susceptible to degradation due to radiation. WCA is calculated for a TID of 13 krad.

4.3 Parametric variation calculation

This WCA uses the JPL [1] method EVA (Extreme Value Analysis). EVA is used for both the derivation of part variations and the combinations of circuit parts values. The EVA method yields very conservative results which represent the absolute boundary conditions for the components and the circuit.

The EVA worst case variation (DP = total parametric variation) for a component is the product of the individual parametric variations, as follows:

$$DP = -1 + (1+dx) * (1+dt) * (1+da) * (1+dr) \text{ // total parametric tolerance}$$

where: DP is the total parametric variation
dx is the part initial tolerance
dt is the variation due to temperature (worst case direction)
da is the variation due to aging and drift
dr is the variation due to radiation degradation

All of the above deltas are normalized as variations from their nominal, which is a $\pm 1\%$ initial tolerance yields a dx of 0.01.

5. Circuit description

The Configuration of DTN SBC is shown as below (Figure 5-1)

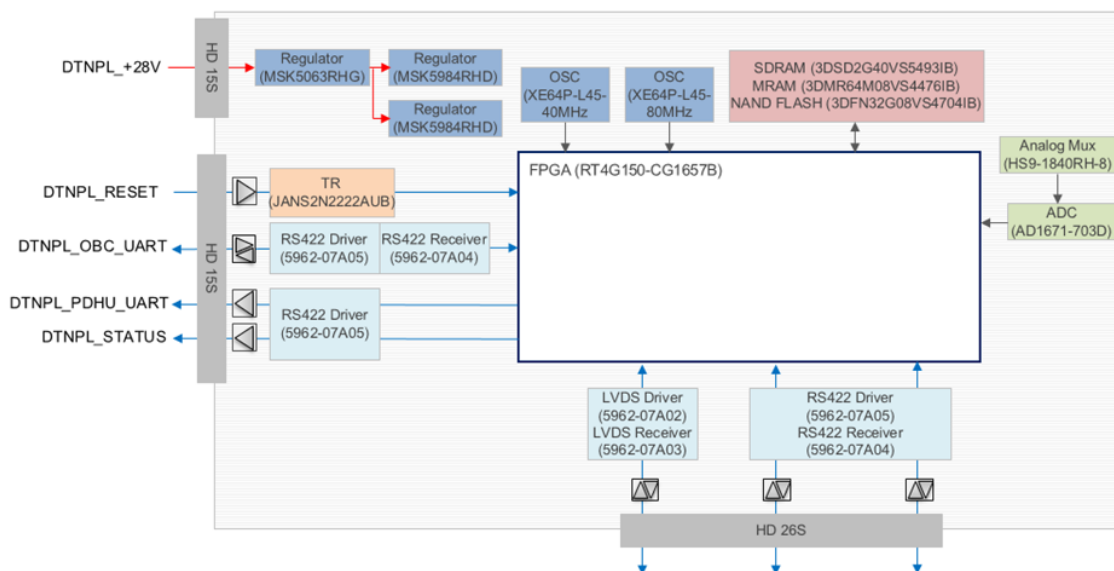


Figure 5-1 SBC Configuration

Functional blocks

(i) Power interface

28V의 입력 전원을 내부의 전원으로 변환한다.

(ii) UART I/F

UART 통신을 위해 구성되었다.

(iii) SpW I/F

SpW 통신을 위해 구성되었다.

(iv) Memory I/F

Memory 는 SDRAM, MRAM, NAND FLASH으로 구성되어 있다.

(v) Reset Circuit

Bi-Level CMD로 reset이 발생하면 reset 된다

2. 6. Evaluation of components total parametric variation and tolerances

In the following the total parametric variation and drift tolerances for the components are calculated. The calculation is based on the EVA approach as described above. Data is taken from the datasheets of the components. For the different components, the following tolerances and drift parameters are taken into the calculation:

Table 2-1 Components Parameters and Tolerances

Component type	Source of variation	Parameter effected
Zener Diodes/ References	<ul style="list-style-type: none"> ■ Initial tolerance ■ Temperature ■ Aging 	<ul style="list-style-type: none"> ■ Reference voltage
Resistors	<ul style="list-style-type: none"> ■ Initial tolerance ■ Temperature ■ Aging drift / EOL Tolerance 	<ul style="list-style-type: none"> ■ Resistance
Capacitors
Linear ICs (OPs)
Digital ICs

5.1 Oscillator

FPGA 에서 사용되는 클럭 소스원이다.

Table 2-2 FPGA DataSheet Reference

Component	Specification	Nominal Value	Initial Tolerance	Temp. Tolerance	Aging / End of Life (EOL) Tolerance	Radiation Tolerance
XE64S-L63-40.000MHz	MIL-PRF-55310	40 MHz	10 ppm	50 ppm (max.)	3 ppm/year	0

DP calculation:

	Tolerance/Drift	Factor	Total
Initial Tolerance	0.000010	1	0.000010
Temperature drift	0.000050	1	0.000050
Aging drift	0.000003	10	0.000030
Radiation drift	0	0	0
		DP(osc)=	0.000090

5.2 Regulator(Power Circuit)

DCDC Conv.에서 제공을 하지 않는 낮은 전압을 생성하는 파트이다.

Table 2-3 Regulator DataSheet Reference

Component	Output Voltage Tolerance	Line Regulation	Load Regulation	Dropout Voltage
MSK5920-1.5KRHS	0.1 %	0.1 %	0.06 %	0.22 V
MSK5920-1.8KRHS	0.1 %	0.1 %	0.06 %	0.22 V

DP calculation:

	Tolerance/Drift
Initial Tolerance	0.1
Line Regulation	0.1
Load Regulation	0.06
DP(reg)=	0.26

5.3 LVDS

Table 2-4 LVDS DataSheet Reference

Component	Maximum Differential Skew & Jitter
3DLVDS3302VS1609 (Driver)	0.6 ns
3DLVDS3302VS1609 (Receiver)	0.2 ns
UT54LVDS031LV	0.4ns
UT54LVDS032LV	0.35ns

5.4 Switching Transistor

Bi-Level CMD 에서 Switch 역할을 하는 TR 이다.

Table 2-5 Switching Transistor DataSheet Reference

Component	Emitter-Base Voltage	Emitter-Base Saturation Voltage
JANS2N2222UA	6.0 Vdc	Min 0.6Vdc Max 2.0 Vdc

5.5 Resistor

일반목적으로 사용된 저항이다.

Table 2-6 Resistor DataSheet Reference

Component	Tolerance	Temp. Tolerance	Aging / End of Life (EOL) Tolerance
M55342K12B---DR	1 %	100ppm	0.5%

DP calculation:

	Tolerance/Drift	Factor	Total
Initial Tolerance	0.01	1	0.01
Temperature drift	0.0001	1	0.0001
Aging drift	0.005	1	0.005
		DP(res)=	0.0151

5.6 Rectifier diode

역전압 방지용 다이오드이다.

Table 2-7 Rectifier Diode DataSheet Reference

Component	Working Peak Reverse Voltage	Maximum Forward Voltage (@If = 1.0 A)	Maximum Forward Voltage (@If = 2.5 A)
JANS1N5806US	150 V	0.875 V	0.975 V

6. Analysis of functional blocks

6.1 Oscillator

6.1.1 Drift Variation of 80MHz Oscillator

Calculation of worst case Min/Max :

$$\Delta F(t) = F(t)_{\text{NOM}} * DP(\text{osc}) = \pm 7,200 \text{ Hz}$$

$$F(t)_{\text{NOM}} = 80,000,000 \text{ Hz}$$

$$DP(\text{osc}) = 0.00009$$

$$F(t) = 80,000,000 \pm 7,200 \text{ Hz}$$

$$F(t)_{\text{Min}} = 79,992,800 \text{ Hz}$$

$$F(t)_{\text{Max}} = 80,007,200 \text{ Hz}$$

6.1.2 Drift Variation of 40MHz Oscillator

Calculation of worst case Min/Max :

$$\Delta F(t) = F(t)_{\text{NOM}} * DP(\text{osc}) = \pm 3,600 \text{ Hz}$$

$$F(t)_{\text{NOM}} = 40,000,000 \text{ Hz}$$

$$DP(\text{osc}) = 0.00009$$

$$F(t) = 40,000,000 \pm 3,600 \text{ Hz}$$

$$F(t)_{\text{Min}} = 39,996,400 \text{ Hz}$$

$$F(t)_{\text{Max}} = 40,003,600 \text{ Hz}$$

6.2 Regulator(Power Circuit)

6.2.1 Output Variation of 1.5V Regulator

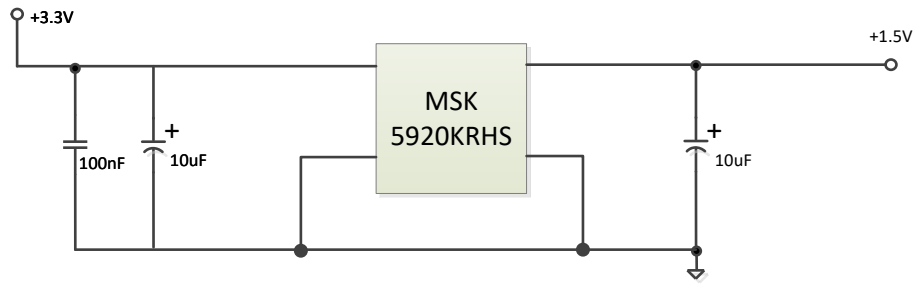


Figure 6-1 Circuit diagram of the +1.5V Power

$V(\text{reg1V5})_{\text{NOM}}$ = Nominal output Voltage value = 1.5 V

Calculation of worst case Min/Max:

$$\Delta V(\text{reg1V5}) = V(\text{reg1V5})_{\text{NOM}} * DP(\text{reg}) = \pm 0.0039 \text{ V}$$

$$V(\text{reg1V5})_{\text{NOM}} = 1.5\text{V}$$

$$DP(\text{reg}) = 0.26 \%$$

$$V(\text{reg1V5}) = 1.5 \pm 0.0039 \text{ V}$$

$$F(t)_{\text{Min}} = 1.4961 \text{ V}$$

$$F(t)_{\text{Max}} = 1.5039 \text{ V}$$

Table 6-1 +1.5V Power Circuit Result

Input Voltage	Nominal Current	Used for	Linear Regulator	Max in regulator	Dropout	Minimum Input Rating
+3.3V	0.5 A	Support FPGA	MSK5920-1.5KRHS	+6.5V	0.22	+1.72V

6.2.2 Output Variation of 1.8V Regulator

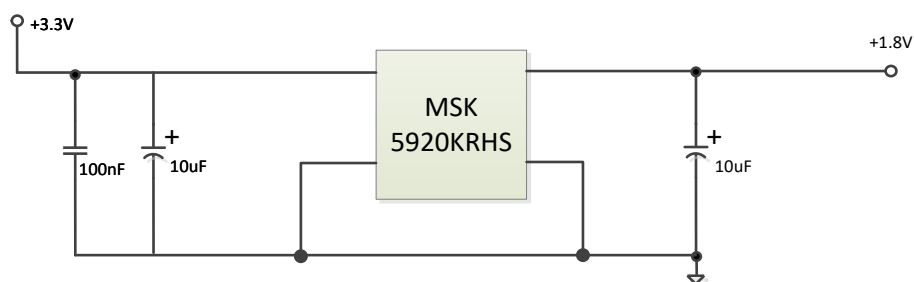


Figure 6-2 Circuit diagram of the +1.8V Power

$V(\text{reg1V8})_{\text{NOM}}$ = Nominal output voltage value = 1.8 V

Calculation of worst case Min/Max:

$$\Delta V(\text{reg1V8}) = V(\text{reg1V8})_{\text{NOM}} * DP(\text{reg}) = \pm 0.00468 \text{ V}$$

$$V(\text{reg1V8})_{\text{NOM}} = 1.8 \text{ V}$$

$$DP(\text{reg}) = 0.26 \%$$

$$V(\text{reg1V8}) = 1.8 \pm 0.00468 \text{ V}$$

$$V(t)_{\text{Min}} = 1.79532 \text{ V}$$

$$V(t)_{\text{Max}} = 1.80468 \text{ V}$$

Table 6-2 +1.8V Power Circuit Result

Input Voltage	Nominal Current	Used for	Linear Regulator	Max in regulator	Dropout	Minimum Input Rating
+3.3 V	0.5 A	FPGA	MSK5920-1.8KRHS	+6.5V	0.22	+2.02V

6.3 Memory I/F

6.3.1 NAND FLASH Timing

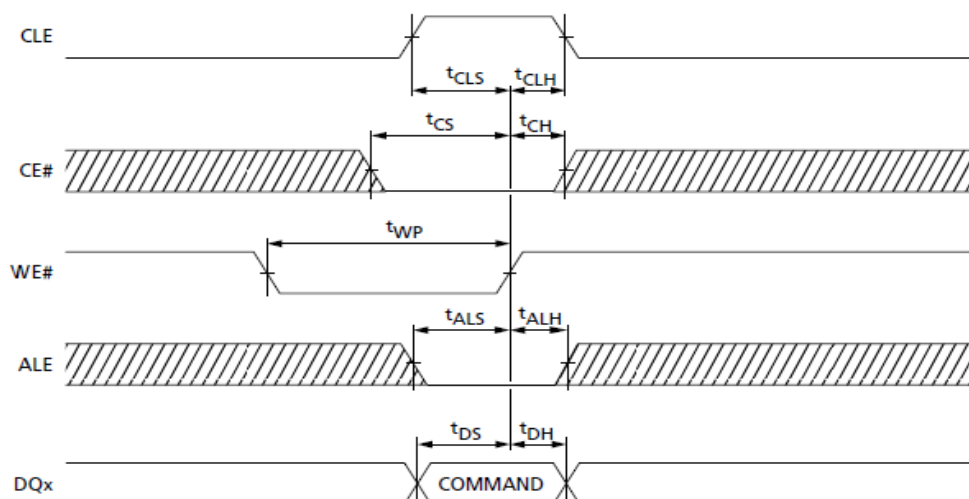


Figure 6-3 NAND FLASH Timing

Table 6-3 NAND FLASH Description

Symbol	Description	Min	Max
t_{CLS}	CLE setup time	10 ns	-
t_{CLH}	CLE hold time	5 ns	-
t_{CS}	CE# setup time	20 ns	-
t_{CH}	CE# hold time	5 ns	-
t_{WP}	WE# pulse width	12 ns	-
t_{ALS}	ALE setup time	10 ns	-
t_{ALH}	ALE hold time	5 ns	-
t_{DS}	Data setup time	10 ns	-
t_{DH}	Data hold time	5 ns	-

40MHz 의 clock 을 사용하므로 각 ALE, CE#, WE#, Data, CLE minimum pulse width 는 25ns 이다.

6.3.2SDRAM Access Delay

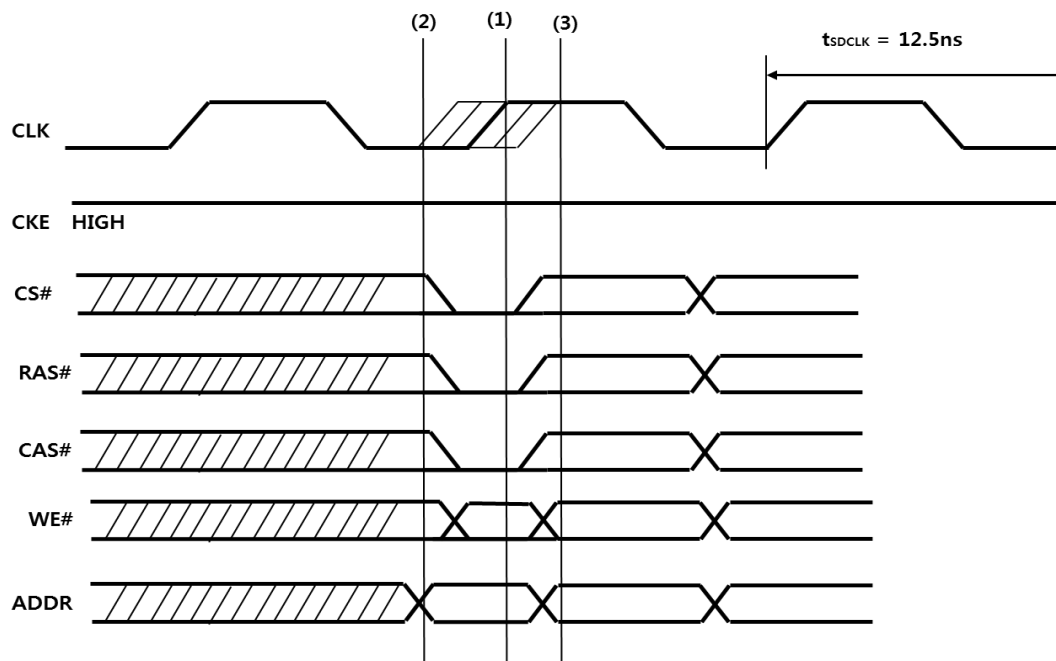


Figure 6-4 SDRAM CLOCK Jitter

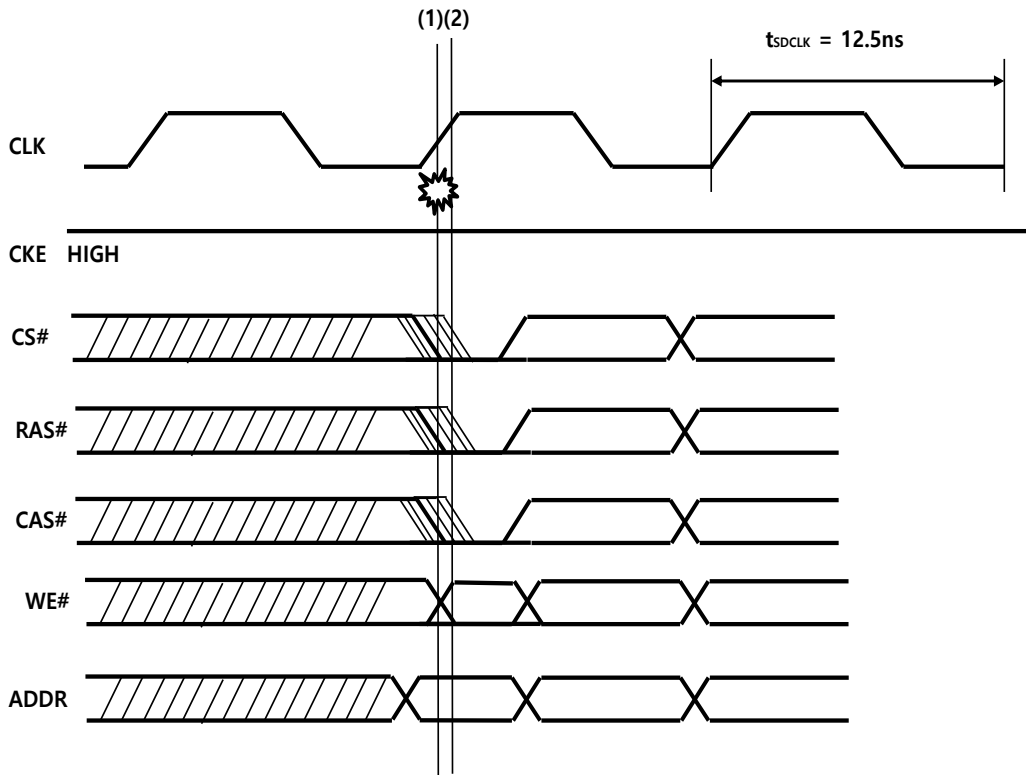


Figure 6-5 SDRAM Control Signals Jitter

80MHz 로 SDRAM 동작에서 jitter 는 one cycle = 12.5ns 이다

6.4 SpaceWire

6.4.1 Synchronization (FPGA)

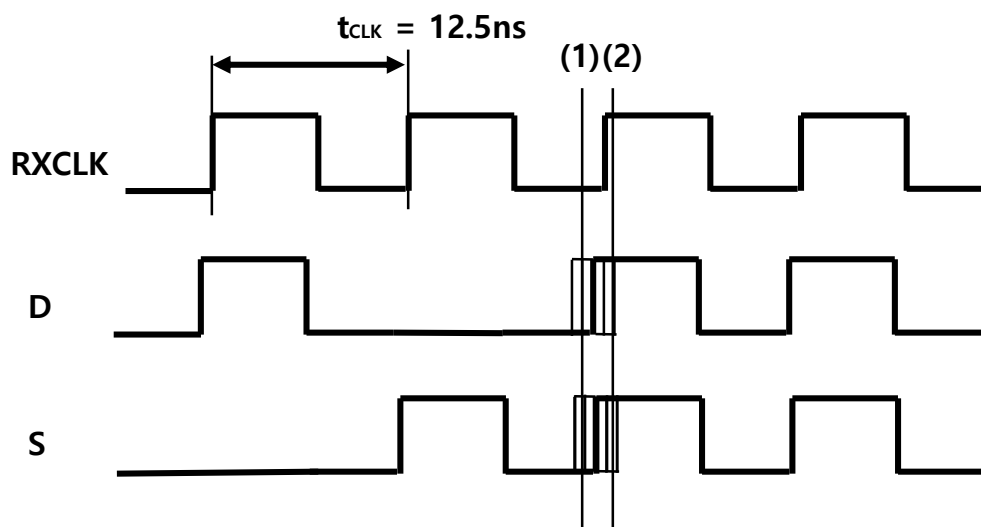


Figure 6-6 FPGA Synchronization

FPGA Receive Clock : 80MHz

Link Speed : 80Mbps

Table 6-4 3DLV3302VS1619 Synchronization

	Data Jitter (t_{jitter})	Strobe Jitter (t_{jitter})	Skew (t_{skew})	Minimum Edge Separation (t_{DS})
Driver (3DLV3302VS1619)	0.6 ns	0.6 ns	1.0 ns	
Cable	0.5 ns	0.5 ns	1.0 ns	
Receiver (3DLV3302VS1619)	0.2 ns	0.2 ns	0.5 ns	
FPGA				1 ns
Total	1.3 ns	1.3 ns	2.5 ns	1 ns

$$\begin{aligned}
 T_{\text{Jitter_Max}} &= t_{\text{Skew}} + 2 * t_{\text{jitter}} + t_{\text{DS}} \\
 &= 2.5 \text{ ns} + 2 * 1.3 \text{ ns} + 1 \text{ ns} = 6.1 \text{ ns}
 \end{aligned}$$

Table 6-5 UT54LVDS031LV Synchronization

	Data Jitter (t_{jitter})	Strobe Jitter (t_{jitter})	Skew (t_{skew})	Minimum Edge Separation (t_{DS})
Driver (UT54LVDS031LV)	0.4 ns	0.4 ns	0.5 ns	
Cable	0.5 ns	0.5 ns	1.0 ns	
Receiver (UT54LVDS032LV)	0.35 ns	0.35 ns	0.5 ns	
FPGA				1 ns
Total	1.25 ns	1.25 ns	2.0 ns	1 ns

$$\begin{aligned}
 T_{\text{Jitter_Max}} &= t_{\text{Skew}} + 2 * t_{\text{jitter}} + t_{\text{DS}} \\
 &= 2.5 \text{ ns} + 2 * 1.25 \text{ ns} + 1 \text{ ns} = 6.0 \text{ ns}
 \end{aligned}$$

7. Summary of component variation

7.1 Oscillator

Table 7-1 Oscillator Variation

Component	Ref.	Nominal Value	IT = Initial Tolerance	DT = Drift Tolerance	DP = Total parametric variance
XE64S-L63- 80.000MHz	OSC	80,000,000 Hz	IT(osc)= 0.000010	DT(osc)= 0.000080	DP(osc)= 0.000090
XE64S-L63- 40.000MHz	OSC	40,000,000 Hz	IT(osc)= 0.000010	DT(osc)= 0.000080	DP(osc)= 0.000090

7.2 Regulator

Table 7-2 Regulator Variation

Component	Ref.	Nominal Value	IT = Initial Tolerance	DT = Drift Tolerance	DP = Total parametric variance
MSK5920-1.5KRHS	Reg	1.5 V	IT(Reg)= 0.1	DT(Reg)= 0.16	DP(Reg)= 0.26
MSK5920-1.8KRHS	Reg	1.8V	IT(Reg)= 0.1	DT(Reg)= 0.16	DP(Reg)= 0.26

7.3 Resistor

Table 7-3 Resistor Variation

Component	Ref.	Nominal Value	IT = Initial Tolerance	DT = Drift Tolerance	DP = Total parametric variance
Resistor	res	-	IT(res)=0.01	DT(res)=0.051	DP(res)=0.0151

8. Analysis Results

The circuit is analysed to determine the Min/Max range of functional responses to initial settings, component tolerances, aging and temperature. Circuit Min/Max responses are compared to required responses and the results are categorized in the summary as follows:

OK: The analysed Min/Max response for this functional block is fully within the specification limits.

Caution: The Min or Max response exceeds the specification limits within $\pm 10\%$.

Alert: The Min or Max response exceeds the specification limits more than $\pm 10\%$.

Analysis results are summarized bellow. Calculation details are provided in the following worksheets.

Table 8-1 Oscillator and Regulator Analysis

Line Item	Functional Block	Component	Parameter Unit	Nominal Value Limit Tolerance	Limit Min / Max	Analyzed Min/ Max	Status
1	Oscillator	XE64S-L63-80.000MHz	F Hz	80,000,000 ($\pm 0.01\%$)	79,992,000 80,008,000	79,993,299 80,006,800	Ok
2	Oscillator	XE64S-L63-40.000MHz	F Hz	40,000,000 ($\pm 0.01\%$)	39,996,000 40,004,000	79,996,400 40,003,600	Ok
3	Regulator	MSK5920-1.5KRHS	V	1.5	1.45 / 1.55	1.4961 / 1.5039	OK
4	Regulator	MSK5920-1.5KRHS	V	1.5	1.75 / 1.85	1.795 / 1.804	OK

Table 8-2 Interface Analysis

Line Item	Interface	Limit Delay Min/Max	Analyzed Delay Min/Max	Description	Status
1	NAND FLASH	25ns -	- 25ns		Ok
2	SDRAM	10ns -	- 12.5ns		Ok
3	FPGA SpaceWire Synchronization	- 12.5 ns	- 6.0 ns		Ok

Table 8-3 Bi-Level TR Analysis

Line Item	Functional Block	Component(s))	Parameter Unit	Nominal Value Limit Tolerance	Limit Min / Max	Analyzed Min/ Max	Status
1	Bi-Level TR	JANS2N2222A UB	Emitter-Base Voltage	-	0 /6	2.948 /3.038	OK